

I claim:

1. A light-emitting structure, comprising:  
a light-emitting diode having an anode and a cathode; and  
a resistive member carried over at least one of said anode and  
said cathode.
2. The structure of claim 1, wherein said resistive member has a  
resistivity and a cross section configured to realize a predetermined  
resistance.
3. The structure of claim 1, wherein said resistive member  
comprises a resistive film.
4. The structure of claim 1, wherein said resistive member  
comprises a thin film resistor.
5. The structure of claim 1, wherein said resistive member  
comprises a thick film resistor.
6. The structure of claim 1, further including a conductive film  
inserted between said resistive member and said light-emitting diode.
7. The structure of claim 1, wherein said resistive member is  
carried over said anode and further including an interconnect  
member coupled to a selected one of said cathode and said resistive  
member.
8. The structure of claim 6, wherein said interconnect member is  
coupled through at least one contact.
9. The structure of claim 6, wherein said interconnect member  
includes a tab that couples to said selected one.
10. The structure of claim 6, further including a wire bond that

couples said interconnect member to said selected one.

11. The structure of claim 1, wherein said resistive member is carried over said cathode and further including an interconnect member coupled to a selected one of said anode and said resistive member.

12. The structure of claim 11, wherein said interconnect member is coupled through at least one contact.

13. The structure of claim 11, wherein said interconnect member includes a tab that couples to said selected one.

14. The structure of claim 11, further including a wire bond that couples said interconnect member to said selected one.

15. The structure of claim 1, wherein said light-emitting diode is a semiconductor light-emitting diode.

16. The structure of claim 1, wherein said light-emitting diode is an organic light-emitting diode.

17. The structure of claim 1, wherein said light-emitting diode is a polymer light-emitting diode.

18. A light-emitting structure, comprising:

a light-emitting diode having an anode and a cathode;

a resistive member carried over a selected one of said anode and said cathode; and

5 first and second contacts respectively on first and second portions of said resistive member.

19. The structure of claim 18, further including a conductive film inserted between said resistive member and said light-emitting diode.

20. The structure of claim 18, wherein said resistive member has a resistivity and a cross section configured to realize predetermined resistances between said first and second contacts and said light-emitting diode.

21. The structure of claim 18, further including first and second interconnect members respectively coupled to said first and second contacts.

22. The structure of claim 18, wherein said resistive member comprises a resistive film.

23. The structure of claim 18, wherein said resistive member comprises a thin film resistor.

24. The structure of claim 18, wherein said resistive member comprises a thick film resistor.

25. The structure of claim 18, wherein said light-emitting diode is a semiconductor light-emitting diode.

26. The structure of claim 18, wherein said light-emitting diode is an organic light-emitting diode.

27. The structure of claim 18, wherein said light-emitting diode is a polymer light-emitting diode.

28. A light-emitting structure, comprising:  
a light-emitting diode having an anode and a cathode; and  
at least first and second spaced resistive members carried over a  
selected one of said anode and said cathode.

29. The structure of claim 28, further including a conductive film inserted between each of said resistive members and said light-emitting diode.

30. The structure of claim 28, wherein each of said resistive members has a resistivity and a cross section configured to realize a respective predetermined resistance.

31. The structure of claim 28, further including an interconnect member coupled to a selected one of said resistive films.

32. The structure of claim 28, wherein said resistive member comprises a resistive film.

33. The structure of claim 28, wherein each resistive member comprises a thin film resistor.

34. The structure of claim 28, wherein each resistive member comprises a thick film resistor.

35. The structure of claim 28, wherein said light-emitting diode is a semiconductor light-emitting diode.

36. The structure of claim 28, wherein said light-emitting diode is an organic light-emitting diode.

37. The structure of claim 28, wherein said light-emitting diode is a polymer light-emitting diode.